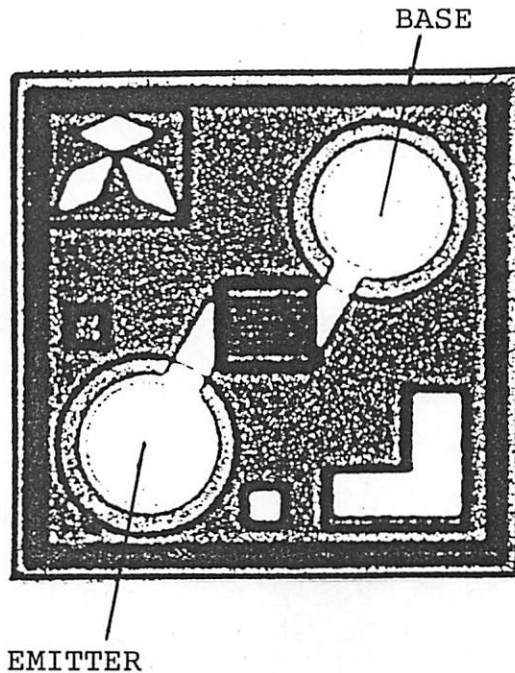


DIE TECHNOLOGY LIMITED



CHIP BACK IS COLLECTOR

E & O E. The supply of dice to this layout can only be guaranteed if it forms part of a specification or the chip identification, if below, is requested. Chip back potential is the level at which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated above. If no potential is given the chip back should be isolated. Nominal metallisation thicknesses are based on manufacturer's information. 1 mil. = 0.001inch. Tolerance +/-3 mils.

<p><u>Approved:</u> <i>[Signature]</i> <u>Date:</u> 16-12-94</p>	<p><u>Metallisation/Thickness (KA)</u> Top : Au 10 Back: AuAs 4</p> <p>Back Potential: Collector Man's. Part No:</p>	<p><u>Chip Identification</u> Line Source: Mask Ref : Process : Version : Geometry :</p>
<p>Corbrook Road Chadderton Lancs. OL9 9SD</p> <p>Tel: 061 626 3827 Fax: 061 627 2341</p>	<p><u>Chip Dimensions (mils.):</u> 11 x 11 x 8</p>	<p><u>Bond Pads:</u> 2.5 ϕ</p>
<p>PHILIPS BFT92</p>		<p>Issue 3</p>